ThinkSystem SR655 V3 overview

Product features, technical specifications

ThinkSystem SR655 V3 product overview

 The SR655 V3 is a 2U one-socket rack server that features the next-generation AMD EPYC 9004 Series processors (codename: Genoa). This high-performance server offers a broad selection of drive and slot configurations and an expansion for various IT workloads.

The SR655 V3 has two machine types:

- 7D9E (three-year warranty)
- 7D9F (one-year warranty)





Features and specifications

Attribute	Specifications
Form factor	2U rack mount
Processor	One AMD EPYC 9004 Series processor with an LGA6096 SP5 socket • Up to 96 Zen4 cores (192 threads) per socket • Up to four GMl3 links at up to 32 GT/s • TDP of up to 320 W
Memory	12 DDR5 DIMM slots • Support for RDIMMs and 3DS RDIMMs – up to 4800 MHz (1DPC) • Maximum memory: 1.5 TB (twelve 128 GB RDIMMs)
Storage	Up to 20 3.5-inch or 40 2.5-inch hot-swap drive bays • Front bay can be 3.5-inch (eight or 12 bays) or 2.5-inch (eight, 16, or 24 bays) • Middle bay can be 3.5-inch (four bays) or 2.5-inch (eight bays) • Rear bay can be 3.5-inch (two or four bays) or 2.5-inch (four or eight bays) • Combinations of SAS/SATA, NVMe, or AnyBay (supporting SAS, SATA, or NVMe) are available Boot Drives: • Two 7 mm drives at the rear • Internal M.2 module supporting up to two M.2 drives

Lenovo

Note: For the latest specifications, refer to the <u>Lenovo Press product guide</u>.

Features and specifications

Attribute	Specifications
Storage controllers	 Up to 16 onboard SATA ports (non-RAID) NVMe Retimer Adapter (PCle 4.0 or PCle 5.0) 12 Gb SAS/SATA RAID adapters with eight, 16, or 32 ports 12 Gb SAS/SATA HBA (non-RAID) with eight or 16 ports
Network interface	Dedicated OCP 3.0 SFF slot with PCle 5.0 interface (rear-accessible) • One port can optionally be shared with the XClarity Controller 2 (XCC2) management processor for Wake-on-LAN and NC-SI support • Additional PCle network adapters supported in the PCle slots
I/O expansion slots	 Up to 10 rear slots can support PCle 4.0/5.0/CXL, supporting up to seven PCle 5.0 slots Up to six onboard NVMe connectors Supported front-accessible PCle slots: two PCle 4.0 x16 slots plus a dedicated OCP 3.0 SFF slot (PCle 4.0 x16) for networking
Cooling	Supported fan types: • Standard fan 6038 (single-rotor, 17000 RPM) • Performance fan 6056 (dual-rotor, 21000 RPM) • Fan redundancy: N + 1 redundancy, one redundant fan rotor • Without riser 3: four hot-swap system fans (fan 6056 only, one redundant fan rotor)

Note: For the latest specifications, refer to the Lenovo Press product guide.



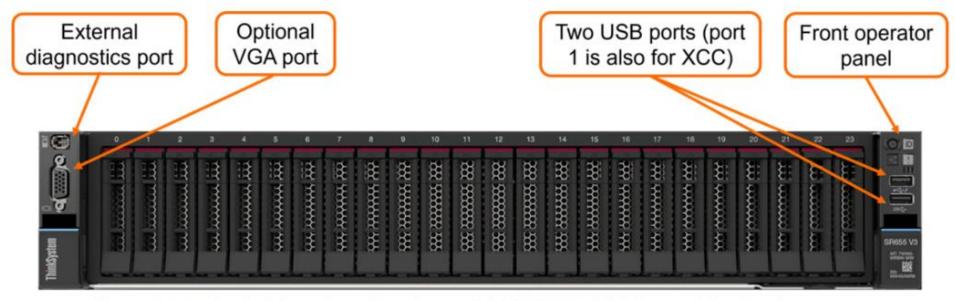
Features and specifications

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Power supplies	Up to two hot-swap power supplies
Management interface	Lenovo XClarity Controller 2 (XCC2)

Note: For the latest specifications, refer to the Lenovo Press product guide.



ThinkSystem SR655 V3 front views



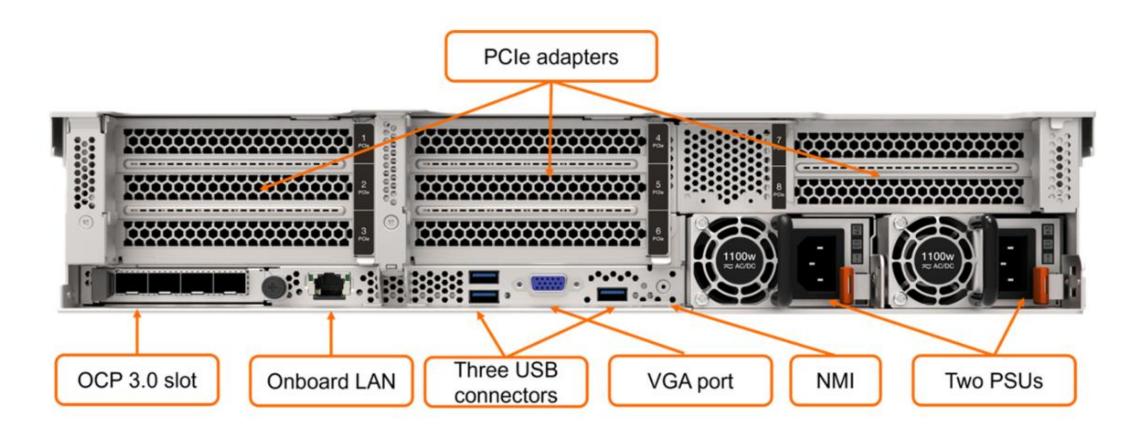
Up to 24 2.5-inch drives (combinations of SAS/SATA, NVMe, and AnyBay)



Up to 12 3.5-inch drives (combinations of SAS/SATA, NVMe, and AnyBay)



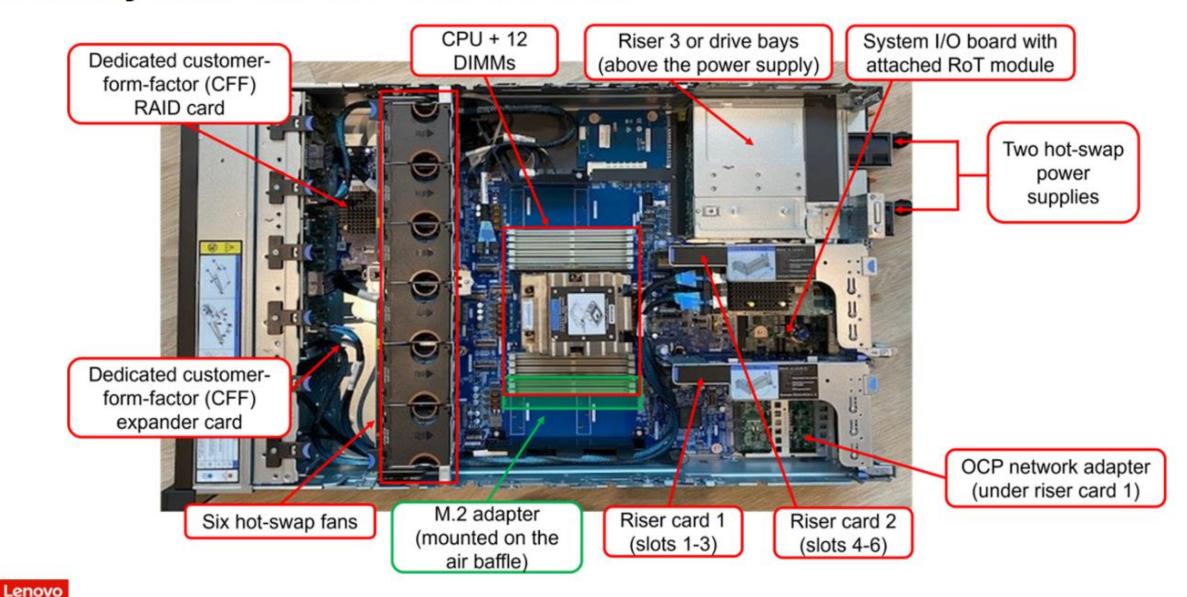
ThinkSystem SR655 V3 rear view



Note: For more information about rear PCle or drive configurations, refer to the <u>System configurations and diagrams</u> section.



ThinkSystem SR655 V3 inside view



ThinkSystem SR655 V3 system board

The SR655 V3 system board assembly has five components:

- Processor board
 - A board containing CPU sockets, PCIe slots, memory slots, and other server component connectors
- Power inverter board (PIB)
 - A board connecting to the processor board (board-to-board connection) that provides system power conversion
- Fan board
 - A board connecting to the processor board (via cable connection) that provides system fan cage power and signal
- System I/O board
 - A board containing the system BMC (XCC2) management port, USB ports, and a VGA connector
 - A Micro SD card slot to extend XCC2 storage space for the backup of firmware and for remote console virtual media
- Firmware and Root of Trust board (RoT module)
 - A mezzanine card containing the Trusted Platform Module (TPM), UEFI firmware, XCC2 firmware, and a silicon Root of Trust

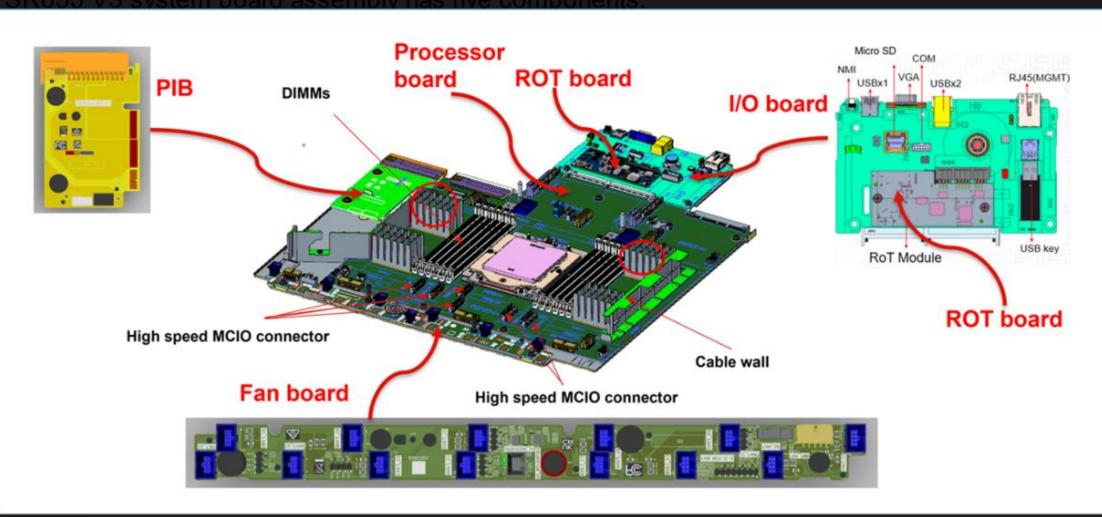
Click **HERE** to see the system board assembly



ThinkSystem SR655 V3 system board

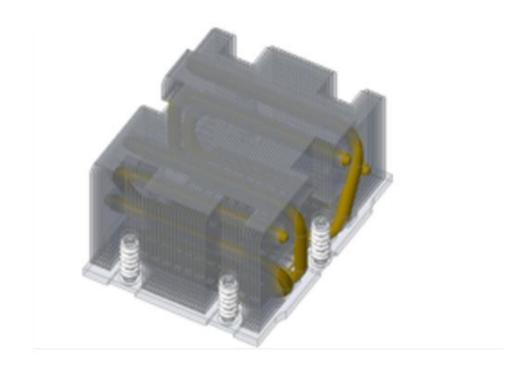


SR655 V3 main board view

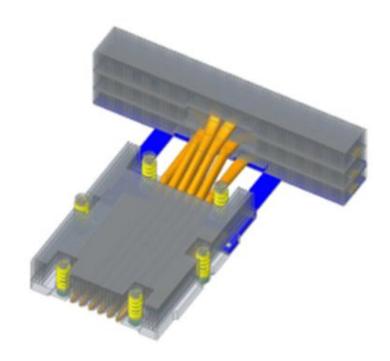


ThinkSystem SR655 V3 processor heat sinks

The SR655 V3 supports two types of heat sink: standard and performance.



Standard (CPU heat sink – 2U in height)
For processors with a TDP of 200 W to 300 W



Performance (CPU heat sink – 1U in height, front fin – 2U in height)

ThinkSystem SR655 V3 air baffles

The SR655 V3 supports two types of air baffle.

